

Specifications

Wafer

備注 (Remark)

1. 材料 (Material)

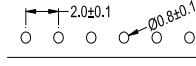
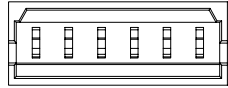
膠芯: PA66 UL94V-0

Housing: PA66 UL94V-0

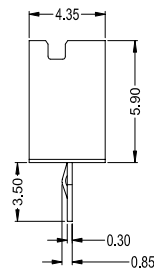
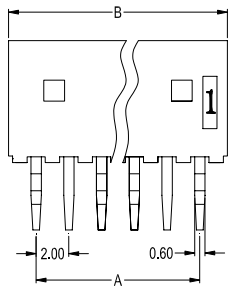
端子: 黃銅

Contact: Brass

2012WV-XX-N0SN



Recommend PCB Layout



2012WV-XX-N0SN

Poles	Dimensions (mm)	
	A	B
02	2.00	6.00
03	4.00	8.00
04	6.00	10.00
05	8.00	12.00
06	10.00	14.00
07	12.00	16.00
08	14.00	18.00
09	16.00	20.00
10	18.00	22.00
11	20.00	24.00
12	22.00	26.00
13	24.00	28.00
14	26.00	30.00
15	28.00	32.00

2012WV-XX-N0SN	Nylon 66 UL 94V-0	Brass	Tin-Plated	2012H	1,000Pcs
PART NO	Material	Material(Pin)	Finish(Pin)	Mates With SWB Housing	Q'ty/Bag

Housing

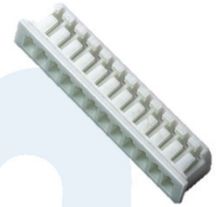
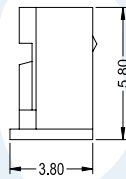
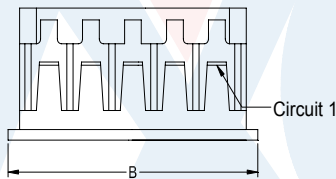
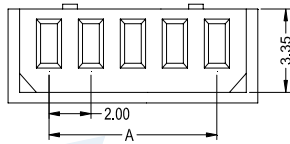
備注 (Remark)

1. 材料 (Material)

膠芯: PA66 UL94V-0

Housing: PA66 UL94V-0

2012H-XX-N0



2012H-XX-N0

Poles	Dimensions (mm)	
	A	B
02	2.00	6.20
03	4.00	8.20
04	6.00	10.20
05	8.00	12.20
06	10.00	14.20
07	12.00	16.20
08	14.00	18.20
09	16.00	20.20
10	18.00	22.20
11	20.00	24.20
12	22.00	26.20
13	24.00	28.20
14	26.00	30.20
15	28.00	32.20

2012H-XX-N0HF	Nylon 66 UL 94V-0 Halogen Free	2012T	2012W	1,000Pcs
2012H-XX-N0	Nylon 66 UL 94V-0			
PART NO	Material	Suitable CSWB Terminal	Mates With SWB Wafer	Q'ty/Bag

Terminal

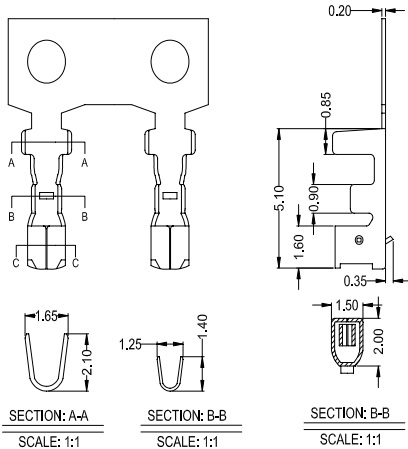
備注 (Remark)

1. 材料 (Material)

端子: 磷青銅

Contact: Phosphor bronze

2012T-PSNX



2012T-PSNX

2012T-PSNB	Phosphor Bronze	AWG#24-30	1.40mm(Max)	Plating Before Stamping: 10~30u" Ni; 40~60u" Sn	2012H	10,000Pcs
2012T-PSN				Stamping Before Plating: 30~50u" Ni; 70~120u" Sn		
PART NO	Material	Wire Range	Insulation O.D.	Finish	Used In SWB Housing	Q'ty/Reel